

Amendments to the Specification

Please amend the specification as follows:

On page 3, please replace the paragraph that starts on line 27 with the words “The invention” and ends on page 4, line 9 with the word “precursor” with the following amended paragraph:

The invention also describes a method of providing the precursor comprising the steps of: a) providing one or more polymers where the polymer or mixture of polymers, respectively, has a melt flow index of 10-100 g/10 min (as measured at 190°C according to ASTMD-1238) and wherein at least one of the polymers has an ethylene unit content of at least 30 % by weight, b) reacting the polymer with a vinyl silane of the formula RR'SiY₂(I), wherein R is a monovalently olefinically unsaturated radical, R' is a monovalent radical free of aliphatic unsaturation and Y is a hydolizable hydrolyzable organic radical, and a free-radical initiator in a heated mixing device to produce a moisture-curable polymer and c) compounding the moisture-curable polymer with one or more thermally-conductive fillers in an amount of at least 60 wt. % of the total weight of the precursor in a heated mixing device. The invention also refers to a method of manufacturing a shaped thermally-conductive material comprising the steps of: a) providing the precursor of present invention, b) thermally forming the precursor to a desired shape and c) crosslinking the precursor.

On page 15, please replace the paragraph that starts on line 28 with the words “The invention” and ends on page 16, line 18 with the word “above” with the following amended paragraph:

The invention also provides a method of manufacturing the precursor of the present invention comprising the steps of a) providing one or more crosslinkable polymers where the polymer or mixture of polymers, respectively, has a melt flow index of 10-100 g/10 min (as measured according to ASTM D-1238 at 190°C) and b) compounding the polymer or polymers, respectively, with a thermally-conductive filler in an amount of at least 60 wt. % of the total weight of the precursor in a heated mixing device. The invention furthermore

provides a preferred method of manufacturing the precursor that specifically relates to embodiments where silane-grafting and moisture curing of the precursor are employed. This method of manufacturing the precursor comprises the steps of a) providing one or more polymers where the polymer or mixture of polymers, respectively, has a melt flow index of 10-100 g/10 min (as measured according to ASTM D-1238 at 190°C) b) reacting the polymer or polymers with a vinyl silane having the formula RR'SiY₂ (I), wherein R is a monovalently olefinically unsaturated radical, R' is a monovalent radical free of aliphatic unsaturation and Y is a hydrolyzable hydrolyzable organic radical, and a free-radical initiator in a heated mixing device to produce a moisture-curable polymer and c) compounding the moisture-curable polymer with one or more thermally-conductive fillers in an amount of at least 60 wt. % of the total weight of the precursor in a heated mixing device. The crosslinkable polymer preferably has an ethylene unit content of at least 30 % by weight with respect to the total weight of the crosslinkable polymer and the vinyl silane preferably has the formula RR'SiY₂. Preferred embodiments of R, R' and Y are described above.